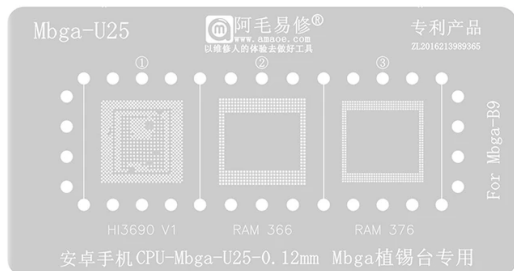


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AMAOE BGA Mbga-U25 stencil reballing CPU HI3690v1 RAM366 RAM376 0,12mm for MBGA-B9

Product ID: 23007

Price: **7.00 EUR**

Product weight: **0.20 kg**

Description:

AMAOE BGA Mbga-U25 stencil reballing CPU HI3690v1 RAM366 RAM376 0,12mm for MBGA-B9 - the sieves are a product made of steel resistant to high temperatures and deformations. Precise laser-cut templates facilitate positioning during work.

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